



Alliance A4 Strip Process Module Configurator

Asset Number
LAM-2003-U

System Serial Number:
STRIP-XY

Process Module Type:
A4-DSQ Stripper
Wafer Size:
8" (200mm)
Wafer Configuration:
SEMI

Process Module Config	
Coil Plating:	
Upper Match Enclosure Fan:	
Turbo Pump:	
TMP Interlock:	
Ballast V85:	
BSC* Surface Finish:	
BSC* Instrumentation:	
Endpoint Filters:	
Monochromator:	
Soft Pump Option:	

Strip Module Config	
Auxiliary Vacuum Port:	Yes
O-Ring:	Fluorosilicone
Optical Leak Detection:	No
Soft Pump Option:	No
UPS:	No

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Special Instructions:

- Strip Module missing critical parts.
- Some Chamber Parts
 - Some Electrical/Control Box Parts